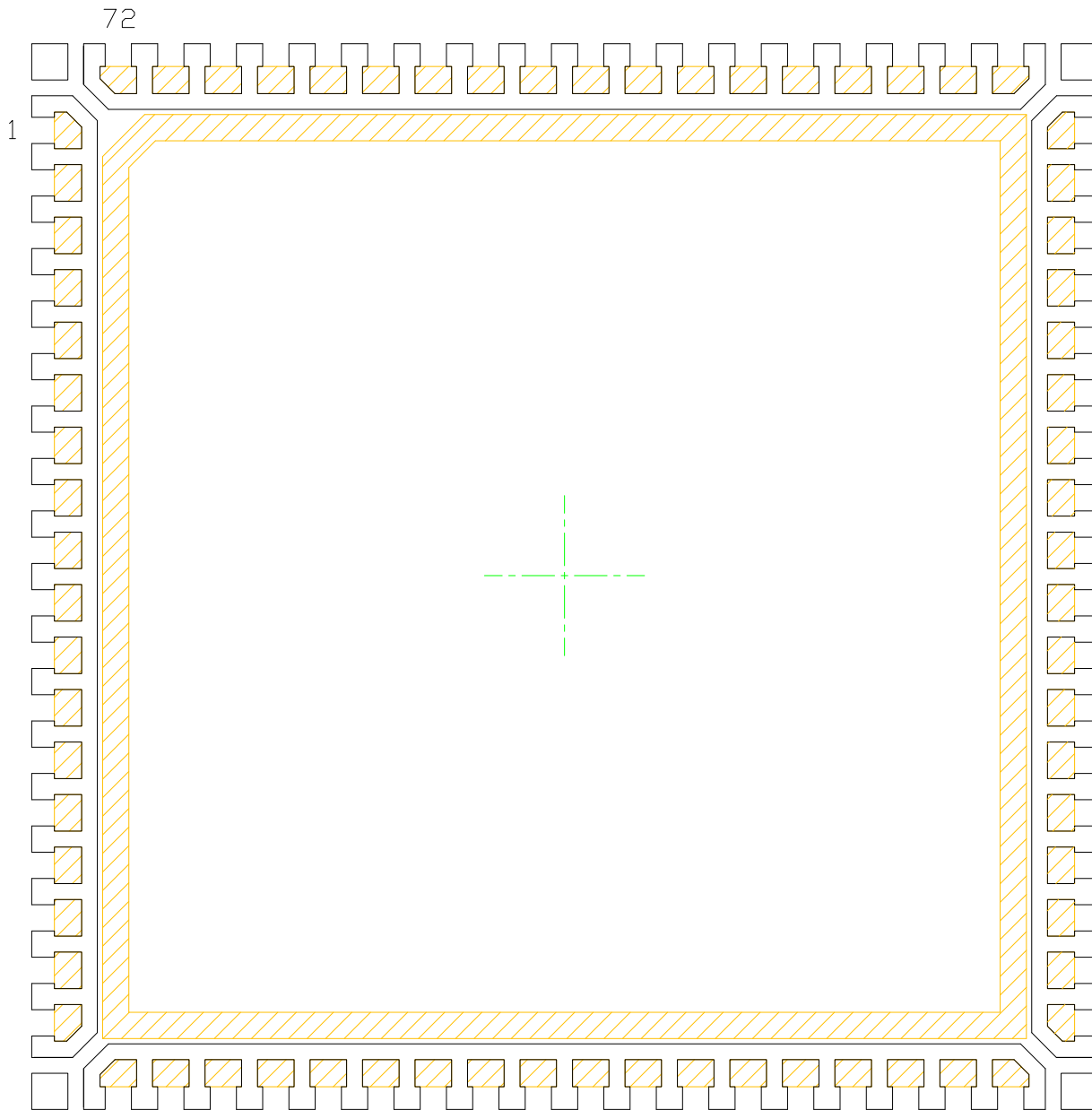



REVISIONS		
REV	DESCRIPTION	DATE
C	CHANGED DAP AND E-PAD SIZES	07-19-17



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 www.promex-ind.com	
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 8.90 x 8.90 mm		
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 8.70 x 8.70 mm	TITLE	
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	QFN 72L 10x10 mm 0.50 PITCH BOND SHELL	
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	LEADFRAME P/N:	REV
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	235-00193	00
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE	FILE NAME
			72L-QFN-10x10-50P-BD.DWG
			SHEET
			1 OF 1